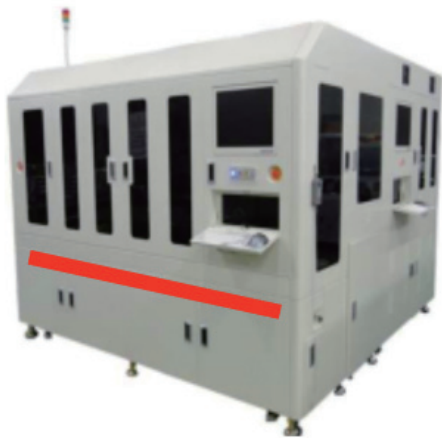


IC Package
substrate



3D AFVI Handler

FCBGA 3D Inspection System (tray type)

- Applicable size: 8x8 to 52.5x52.5mm
- Device thickness: 0.2mm to 1.6mm (typically 0.38mm)
- JEDEC tray: 135.9x315mm (7~13mm T)
- Dual tray feeding system
- Main inspection item: bump, warpage, cop
- UPH: see below (based on 10ea reject sorting)
(For FCBGA, coin bump)

